

FIG. 6 **(**a) (b) 116 Ŝ5 1,10 17 OK 22 -17 lla 11d 22 22/ NG 17 17

22

11e

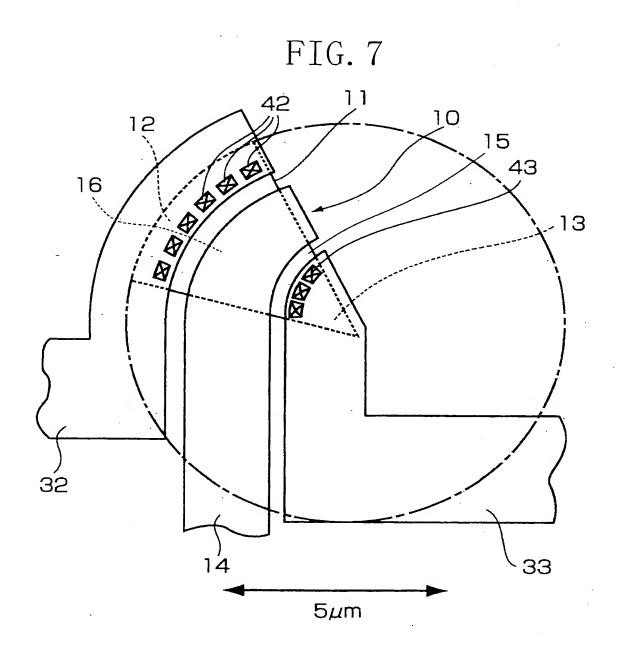


FIG. 8

(d) (a) (4) Protective Oxide Film Formation (1) Oxide Film Formation 56 52 52 51 51 (e) **(**b) (5) Resist Patterning (2) a-Si Film Formation + Channel Doping 52 51 53 -52 **(f)** 51 (6) Dry Etching 56 (c) 52 (3) Laser Anneal 51 55 (g) 53 (7) Resist Removal 52 56 51 52 51



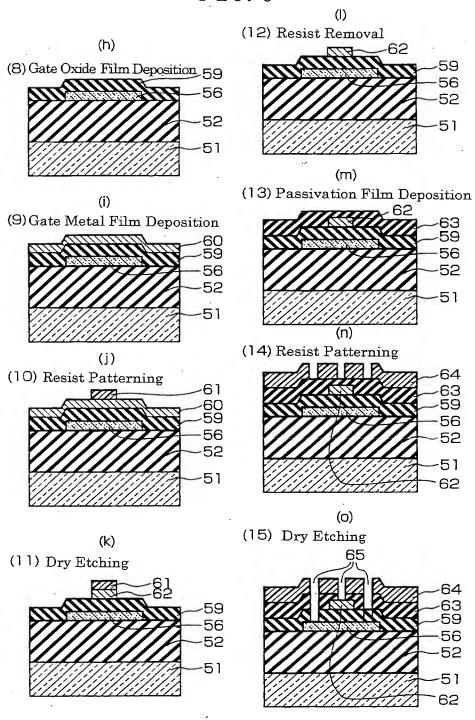
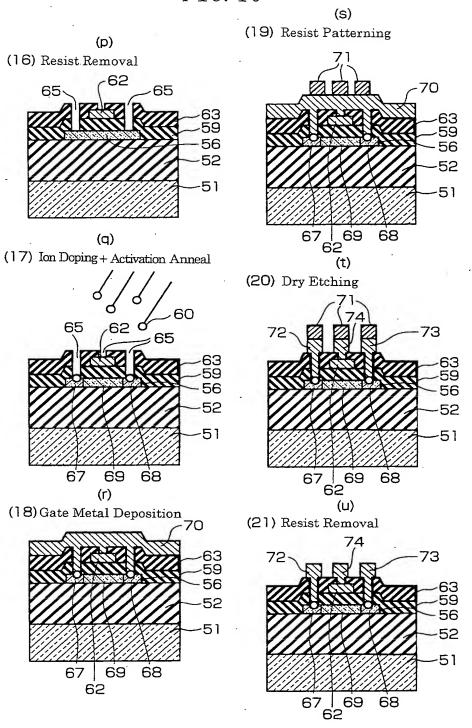


FIG. 10



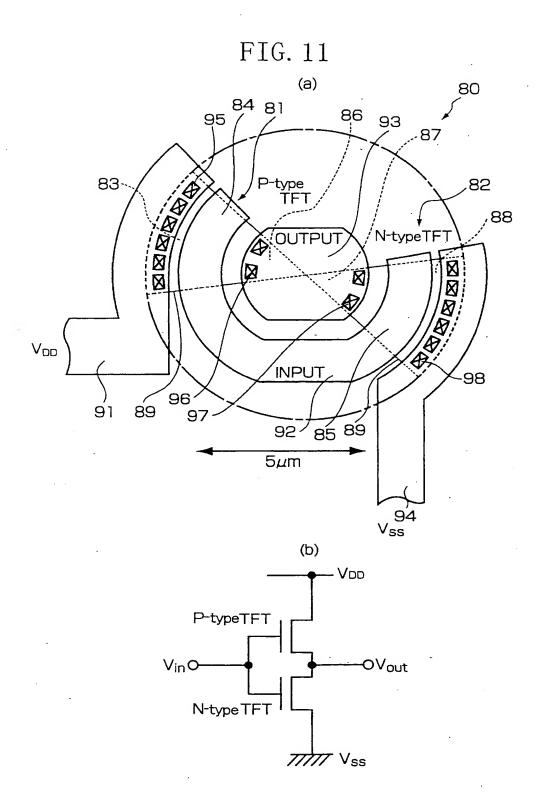


FIG. 12

